

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Zvi Or-Bach	06/01/2012
RECEIVING PARTY DATA	
Name:	MonolithIC 3D Inc.
Street Address:	3555 Woodford Drive
City:	San Jose
State/Country:	CALIFORNIA
Postal Code:	95124
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13041405
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Email:	Brian@MonolithIC3D.com
Correspondent Name:	Brian Cronquist
Address Line 1:	3555 Woodford Drive
Address Line 4:	San Jose, CALIFORNIA 95124
ATTORNEY DOCKET NUMBER:	M3D-015
NAME OF SUBMITTER:	Brian Cronquist
Total Attachments: 1 source=M3D-015_Assignment_Hr1_s#page1.tif	

OP \$40.00 13041405

**ASSIGNMENT**

Whereas, we, **Zvi Or-Bach, residing at 3555 Woodford Drive, San Jose, California 95124,**  
**respectively;** (hereinafter called "Assignor(s)"), have made a certain invention, and executed Patent Application entitled:

**SEMICONDUCTOR DEVICE AND STRUCTURE FOR HEAT REMOVAL**

as described in Patent Application Serial No. 13/041,405 and filed on March 6, 2011; and

Whereas, MonolithIC 3D Inc., a company located at 3555 Woodford Drive, San Jose, California 95124  
 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the  
 invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every  
 Country (hereinafter called the "Designated Countries").

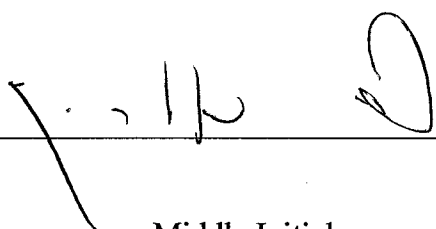
Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the  
 entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the  
 Designated Countries as regards the United States application and the invention disclosed therein (including  
 rights of priority based on the United States application), and I/we will execute without further consideration all  
 papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model  
 registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

DATE on 6.1.11

		
(Zvi		Or-Bach)
First Name	Middle Initial	Last Name